**CLAIMS**

1. A printed circuit board (PCB) including:

a) an upper surface having one or more PCB terminals thereon, each PCB terminal adapted for connection to one of one or more components at a component terminal of each of the one or more components;

b) one or more platforms located adjacent to corresponding component terminals,

(i) wherein each platform supports one of the one or more components;

(ii) wherein a portion of each component overhangs a corresponding platform;

c) a substrate;

d) a masking layer, the platforms being fabricated on the masking layer, wherein the masking layer has a greater surface area than the platforms; and

e) a solder layer for each component, each component resting on a corresponding platform,

(i) wherein the solder layer is between:

(1) an underside of the overhang portion of the component includes a component terminal of the component; and

(2) a corresponding PCB terminal; and

(iii) wherein an air gap is disposed between the solder layer and the platform adjacent the solder layer.

2. The PCB of claim 1, wherein each platform has only one component on the platform.

3. The PCB of claim 2, wherein each platform is in the shape of a planar rectangular layer with a thickness up to 1mm.

4. The PCB of claim 3,

wherein the masking layer includes three rectangular masking layers;

wherein the first and second rectangular masking layers are located along two opposite ends of the PCB and cover the full length of the PCB;

wherein the third rectangular masking layer is located across the middle of the PCB and connects the first and rectangular masking layers; and

wherein the PCB has a single platform located on top of the third masking layer.

5. A printed circuit board (PCB) having one or more PCB terminals located on an upper surface, the PCB including:

a) one or more platforms, the platforms being located adjacent to the one or more PCB terminals;

b) one or more components located on the platforms such that a portion of the component overhangs the platform;

(i) wherein an underside of the overhang portion of the component includes a component eterminal; and

(ii) wherein the the overhang portion of the component is positioned substantially above the corresponding PCB terminal;

c) a solder layer provided between the underside of the overhang portion of the component and the PCB terminal, the solder layer connecting the PCB terminal and corresponding component terminal;

d) a substrate; and

e) a masking layer on the substrate,

(i) wherein the platforms are provided on the masking layer,

(ii) wherein the masking layer has a greater surface area than the platforms; and

(iii) wherein an air gap is disposed between the solder layer and the platform adjacent the solder layer.

6. The PCB of claim 5, wherein each platform has only one component on the platform.

7. The PCB of claim 6, wherein each platform is in the shape of a planar rectangular layer with a thickness up to 1mm.

8. The PCB of claim 7,

wherein the masking layer includes three rectangular masking layers;

wherein the first and second rectangular masking layers are located along two opposite ends of the PCB and cover the full length of the PCB;

wherein the third rectangular masking layer is located across the middle of the PCB and connects the first and rectangular masking layers; and

wherein the PCB has a single platform located on top of the third masking layer.

9. A method of fabricating a printed circuit board (PCB) comprising:

a) providing a substrate having one or more PCB terminals fabricated on the upper surface thereof adapted for connection to corresponding component terminals on one or more components;

b) fabricating one or more platforms onto the PCB upper surface, adjacent to the one or more PCB terminals;

c) adding the one or more components onto corresponding platforms, such that a portion of each component overhangs the platform and rests above a corresponding PCB terminal, the overhang portion including a component terminal on its underside, wherein each platform has only one component connected; and

d) forming a solder or weld connection between each PCB terminal and corresponding component terminal, wherein a gap between the solder or weld connection and the platform is filled with air.